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# Cypress Semiconductor Product Qualification Plan

**QTP# 113005****January 2013**

<b>64K Serial Non-Volatile SRAM Product Family S8 Technology, CMI (Fab 4)</b>	
<b>CY14MB064Q2B CY14MB064Q1B</b>	<b>3V, 64-KBIT (8 K X 8) SPI NVSRAM</b>
<b>CY14ME064Q2B CY14ME064Q1B</b>	<b>5V, 64-KBIT (8 K X 8) SPI NVSRAM</b>
<b>CY14MB064J2A CY14MB064J1A</b>	<b>3V, 64-KBIT (8 K X 8) SERIAL (I2C) NVSRAM</b>
<b>CY14ME064J2A CY14ME064J1A</b>	<b>5V, 64-KBIT (8 K X 8) SERIAL (I2C) NVSRAM</b>

## **CYPRESS TECHNICAL CONTACT FOR QUALIFICATION DATA:**

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### QUALIFICATION HISTORY

Qual Report	Description of Qualification Purpose	Date Comp
071304	To qualify S8 SONOS technology and 4M nvSRAM devices CY14B104L / CY14B104N (7C14104AC base die) using S8TNV-5R, fabricated at Cypress Minnesota CMI (Fab4)	Nov 2008
102204	To qualify Indus 1M serial nvSRAM using S8 technology at CMI (Fab4)	June 2010
122802	To qualify Indus 1M serial nvSRAM 5V device option	Sep 2012
113005	To Qualify Manas, 64K Serial NVSRAM, in S8TNV-5R Technology, CMI Fab4	Nov 2012

PRODUCT DESCRIPTION (for qualification)	
Purpose: Qualification of Manas, 64K Serial NVSRAM, in S8TNV-5R Technology, CMI Fab4	
Marketing Part #:	CY14MB064Q2B, CY14MB064Q1B, CY14ME064Q2B, CY14ME064Q1B, CY14MB064J2A, CY14MB064J1A, CY14ME064J2A, CY14ME064J1A
Device Description:	3V & 5V Commercial/Industrial, available in 8Lead SOIC
Cypress Division:	Cypress Semiconductor Corporation – MPD

TECHNOLOGY/FAB PROCESS DESCRIPTION – S8TNV-5R			
Number of Metal Layers:	3	Metal Composition:	Metal 1: 100A Ti / 3200A Al -0.5%Cu / 300A TiW Metal 2: 100A Ti / 3200A Al -0.5%Cu / 300A TiW Metal 3: 150A Ti / 7200A Al -0.5%Cu / 300A TiW
Passivation Type:	7000 +/- 2000A Nitride		
Generic Process Technology/Design Rule (drawn):	S8TNV-5R/0.13µm		
Gate Oxide Material/Thickness (MOS):	SiO2 /110A & SiO2/32A		
Name/Location of Die Fab (prime) Facility:	Cypress Semiconductor -- Bloomington, MN		
Die Fab Line ID/Wafer Process ID:	Fab4 / S8TNV-5		

### PACKAGE AVAILABILITY

PACKAGE	ASSEMBLY FACILITY SITE
8L-SOIC	CML-RA

**Note:** Package Qualification details upon request

MAJOR PACKAGE INFORMATION USED IN THIS QUALIFICATION	
Package Designation:	SZ815
Package Outline, Type, or Name:	8-Lead SOIC
Mold Compound Name/Manufacturer:	MP8500/ Nitto
Mold Compound Flammability Rating:	V-O per UL94
Oxygen Rating Index:	None
Lead Frame Material:	Copper
Lead Finish, Composition / Thickness:	NiPdAu
Die Backside Preparation Method/Metallization:	Backgrind
Die Separation Method:	100% Saw
Die Attach Supplier:	Henkel
Die Attach Material:	QMI-509
Die Attach Method:	Epoxy
Bond Diagram Designation:	001-71917
Wire Bond Method:	Thermosonic
Wire Material/Size:	Au / 0.9 mil
Thermal Resistance Theta JA °C/W:	101.8°C/W
Package Cross Section Yes/No:	N/A
Assembly Process Flow:	001-69914
Name/Location of Assembly (prime) facility:	CML – RA
MSL Level	3
Reflow Profile	260C

# RELIABILITY TESTS PERFORMED PER SPECIFICATION REQUIREMENT

Stress/Test	Test Condition (Temp/Bias)	Result P/F
High Temperature Operating Life Early Failure Rate (EFR)	Dynamic Operating Condition, 2.7V/3.3V/5.5V, 150°C/48H or 125°C/96H JESD22-A-108-B	P
High Temperature Operating Life Latent Failure Rate (LFR)	Dynamic Operating Condition, 2.7V/3.3C/5.5V, 150°C/500H or 125°C/1000H JESD22-A-108-B	P
Pre/Post LFR AC/DC Char	AC/DC Critical Parameter Char at LFR 0hrs, 80hrs & 500hrs	P
Endurance	1 Million Cycles @ 90C, Per datasheet	P
Data Retention	150°C, 1000 Hours	P
Temperature Cycle	-65°C to 150°C, JESD22-A-104 500 Cycles, Require Precondition	P
High Accelerated Saturation Test (HAST)	130°C, 3.63V, 85%RH, JESD22-A-110-B 128 Hours, Require Precondition	P
Pressure Cooker	121°C/100%RH, JESD22-A102-C 168 Hours, Require Precondition	P
Precondition	JESD22 Moisture Sensitivity	P
Electrostatic Discharge Human Body Model (ESD-HBM)	2,200V, JESD22-A114E	P
Electrostatic Discharge Charge Device Model (ESD-CDM)	500V, JESD22-C101C	P
Electrostatic Discharge Machine Model (ESD-MM)	200V, JESD22-A115-A	P
Latch-up Sensitivity	5.4V,± 200mA, 125°C, EIA/JESD78	P
Age Bond Strength	Mil-Std-883, Method 2011	P
Acoustic	MSL 3	P
Soft Error (Alpha Particle)	JESD89A	P
Soft Error (Neutron/Proton)	JESD89A	P
SEM X-Section	XY audit at center wafer and edge wafer	P
Low Temperature Operating Life Test	Dynamic Operating Condition, 2.7V, -30°C, 500 Hours	P
High Temp Steady State Life Test	Static Operating Condition, 2.7V, 150°C, 1000 Hours	P

### RELIABILITY FAILURE RATE SUMMARY

Stress/Test	Device Tested/ Device Hours	# Fails	Activation Energy	Thermal AF <sup>4</sup>	Failure Rate
High Temperature Operating Life Early Failure Rate	4,617 Devices <sup>1</sup>	0	N/A	N/A	0 PPM
High Temperature Operating Life <sup>1,2</sup> Long Term Failure Rate	537,816 DHRs <sup>2</sup> 188,640 DHRs <sup>3</sup>	0 0	0.7 0.7	170 55	9 FITs

<sup>1</sup> Assuming an ambient temperature of 55°C and a junction temperature rise of 15°C.

<sup>2</sup> Chi-squared 60% estimations used to calculate the failure rate.

<sup>3</sup> Thermal Acceleration Factor is calculated from the Arrhenius equation

$$AF = \exp \left[ \frac{E_A}{k} \left[ \frac{1}{T_2} - \frac{1}{T_1} \right] \right]$$

where:

E<sub>A</sub> = The Activation Energy of the defect mechanism.

k = Boltzmann's constant = 8.62x10<sup>-5</sup> eV/Kelvin.

T<sub>1</sub> is the junction temperature of the device under stress and T<sub>2</sub> is the junction temperature of the device at use conditions.

<sup>1</sup> EFR failure rate data is based on QTP#113005

<sup>2</sup> LFR data from QTP#071304 & QTP#102204

<sup>3</sup> LFR data from QTP#122802 & QTP113005



## Reliability Test Data

QTP #: 071304

Device	Fab Lot #	Assy Lot #	Assy Loc	Duration	Samp	Rej	Failure Mechanism
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**STRESS: HIGH TEMP DYNAMIC OPERATING LIFE-EARLY FAILURE RATE, 150C, 2.7V, Vcc Max**

CY14B104L (7C14104AC)	4811240	610819876	CML-RA	48	1222	0	
CY14B104L (7C14104AC)	4814841	610832326	CML-RA	48	1316	0	
CY14B104L (7C14104AC)	4817306	610830615	CML-RA	48	932	0	
CY14B104L (7C14104AC)	4819437	610842294	CML-RA	48	813	0	

**STRESS: HIGH TEMP DYNAMIC OPERATING LIFE-LATENT FAILURE RATE, 150C, 2.7V, Vcc Max**

CY14B104L (7C14104AC)	4811240	610819876	CML-RA	500	120	0	
CY14B104L (7C14104AC)	4814841	610832326	CML-RA	500	120	0	
CY14B104L (7C14104AC)	4817306	610830615	CML-RA	500	119	0	
CY14B104L (7C14104AC)	4819437	610842294	CML-RA	500	119	0	

**STRESS: Pre-/ Post HIGH TEMP DYNAMIC OPERATING LIFE-LATENT FAILURE RATE CHAR**

CY14B104L (7C14104AC)	4811240	610819876	CML-RA	80/500	10	0	
CY14B104L (7C14104AC)	4814841	610832326	CML-RA	80/500	10	0	
CY14B104L (7C14104AC)	4817306	610830615	CML-RA	80/500	10	0	
CY14B104L (7C14104AC)	4819437	610842294	CML-RA	80/500	10	0	

**STRESS: ENDURANCE, 200K CYCLES, 90C**

CY14B104L (7C14104AC)	4811240	610819876	CML-RA	COMP	80	0	
CY14B104L (7C14104AC)	4817305	610841260	CML-RA	COMP	77	0	
CY14B104L (7C14104AC)	4817306	610830615	CML-RA	COMP	160	0	
CY14B104L (7C14104AC)	4819437	610842294	CML-RA	COMP	80	0	
CY14B104L (7C14104AC)	4817306/4818074		CML-RA	COMP	3307	0	

**STRESS: DATA RETENTION, 150C**

CY14B104L (7C14104AC)	4817306	610830615	CML-RA	1000	77	0	
CY14B104L (WAFER)	4817306	610830615	CML-RA	1008	228	0	
CY14B104L (7C14104AC)	4817305	610841260	CML-RA	1000	80	0	
CY14B104L (WAFER)	4817305	610841260	CML-RA	1008	216	0	
CY14B104L (7C14104AC)	4818074	N/A	CML-RA	1000	80	0	
CY14B104L (WAFER)	4818074	N/A	CML-RA	1008	402	0	





## Reliability Test Data

QTP #: 071304

Device	Fab Lot #	Assy Lot #	Assy Loc	Duration	Samp	Rej	Failure Mechanism
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**STRESS: ESD-HUMAN BODY CIRCUIT PER JEDEC EIA/JESD22-A114-B, 2,200V**

CY14B104L (7C14104AC)	4807004	610812949	CML-RA	COMP	8	0	
CY14B104L (7C14104AC)	4817306	610830615	CML-RA	COMP	8	0	
CY14B104L (7C14104AC)	4811240	610819876	CML-RA	COMP	8	0	

**STRESS: ESD-CHARGE DEVICE MODEL, 500V**

CY14B104L (7C14104AC)	4807004	610812949	CML-RA	COMP	9	0	
CY14B104L (7C14104AC)	4817306	610830615	CML-RA	COMP	9	0	
CY14B104L (7C14104AC)	4811240	610819876	CML-RA	COMP	9	0	

**STRESS: ESD-MACHINE MODEL, 200V**

CY14B104L (7C14104AC)	4807004	610812949	CML-RA	COMP	5	0	
CY14B104L (7C14104AC)	4817306	610830615	CML-RA	COMP	5	0	
CY14B104L (7C14104AC)	4811240	610819876	CML-RA	COMP	5	0	

**STRESS: HI-ACCEL SATURATION TEST, 130C, 85%RH, 1.98V, PRE COND 192 HR 30C/60%RH, MSL3**

CY14B104L (7C14104AC)	4811240	610819876	CML-RA	128	77	0	
CY14B104L (7C14104AC)	4814841	610832326	CML-RA	128	80	0	
CY14B104L (7C14104AC)	4817306	610830615	CML-RA	128	77	0	

**STRESS: PRESSURE COOKER TEST, 121C, 100%RH, 15 Psig, PRE COND 192 HR 30C/60%RH, MSL3**

CY14B104L (7C14104AC)	4807004	610812949	CML-RA	168	77	0	
CY14B104L (7C14104AC)	4814841	610832326	CML-RA	168	80	0	
CY14B104L (7C14104AC)	4817306	610830615	CML-RA	168	77	0	

**STRESS: TEMPERATURE CYCLE COND. C, -65C TO 150C, PRE COND 192 HRS 30C/60%RH, MSL3**

CY14B104L (7C14104AC)	4807004	610812949	CML-RA	1000	77	0	
CY14B104L (7C14104AC)	4817306	610830615	CML-RA	1000	80	0	
CY14B104L (7C14104AC)	4814841	610832326	CML-RA	500	80	0	

**STRESS: STATIC LATCH-UP TESTING, 125C, 5.4V,  $\pm 200$ mA**

CY14B104L (7C14104AC)	4807004	610812949	CML-RA	COMP	6	0	
CY14B104L (7C14104AC)	4814841	610832326	CML-RA	COMP	6	0	
CY14B104L (7C14104AC)	4819437	610842294	CML-RA	COMP	6	0	



## Reliability Test Data

QTP #: 071304

Device	Fab Lot #	Assy Lot #	Assy Loc	Duration	Samp	Rej	Failure Mechanism
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**STRESS: AGE BOND**

CY14B104L (7C14104AC)	4807004	610812949	CML-RA	COMP	10	0	
CY14B104L (7C14104AC)	4817306	610830615	CML-RA	COMP	10	0	
CY14B104L (WAFER)	4818074	N/A	CML-RA	COMP	10	0	

**STRESS: ACOUSTIC-MSL3**

CY14B104L (7C14104AC)	4807004	610812949	CML-RA	COMP	15	0	
CY14B104L (7C14104AC)	4817306	610830615	CML-RA	COMP	15	0	
CY14B104L (7C14104AC)	4814841	610832326	CML-RA	COMP	15	0	

**STRESS: SER – ALPHA PARTICLE, 3-TEPM, 3-VOLTAGE, FIT=550 FIT/Mbit @ 85C, Vcc Nom**

CY14B104L (7C14104AC)	4811240	610819876	CML-RA	COMP	3	0	
CY14B104L (7C14104AC)	4817306	610830615	CML-RA	COMP	3	0	
CY14B104L (7C14104AC)	4819437	610842294	CML-RA	COMP	3	0	

**STRESS: SER – NEUTRON/PROTON**

CY14B104L (7C14104AC)	4808220	N/A	CML-RA	COMP	3	0	
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**STRESS: LOW TEMPERATURE OPERATING LIFE TEST, -30C, 2.7V, Vcc Max**

CY14B104L (7C14104AC)	4817306	610830615	CML-RA	500	77	0	
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**STRESS: HIGH TEMP STEADY STATE LIFE TEST, 150C, 2.7V, Vcc Max**

CY14B104L (7C14104AC)	4811240	610819876	CML-RA	1000	76	0	
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## Reliability Test Data

**QTP #: 102204**

Device	Fab Lot #	Assy Lot #	Assy Loc	Duration	Samp	Rej	Failure Mechanism
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**STRESS: HIGH TEMP DYNAMIC OPERATING LIFE-EARLY FAILURE RATE, 150C, 3.3V, Vcc Max**

CY14MB064Q2A (7C1436B5A)	4033346	611113629	CML-RA	48	631	0	
CY14MB064J2 (7C14104B)	4033346	611113777	CML-RA	48	1461	0	
CY14B101Q2A (7C1431B5A)	4034960	611109619	M-PHIL	48	1073	0	
CY14B101Q1A (7C1431B9A)	4050477	611118869	CML-RA	48	883	0	

**STRESS: HIGH TEMP DYNAMIC OPERATING LIFE-LATENT FAILURE RATE, 150C, 3.3V, Vcc Max**

CY14B101Q2A (7C1431B5A)	4034960	611109619	M-PHIL	80	1050	0	
CY14B101Q2A (7C1431B5A)	4034960	611109619	M-PHIL	168	130	0	
CY14MB064Q2A (7C1436B5A)	4033346	611113629	CML-RA	80	618	0	
CY14MB064Q2A (7C1436B5A)	4033346	611113629	CML-RA	168	194	0	
CY14MB064J2 (7C14104B)	4033346	611113777	CML-RA	80	1442	0	
CY14B101Q1A (7C1431B9A)	4050477	611118869	CML-RA	168	128	0	

**STRESS: Pre-/ Post HIGH TEMP DYNAMIC OPERATING LIFE-LATENT FAILURE RATE CHAR**

CY14B101Q1A (7C1431B9A)	4050477	611118869	CML-RA	COMP	10	0	
CY14ME064Q2A (7C1436E5A)	4050477	611118870	CML-RA	COMP	10	0	

**STRESS: ENDURANCE, 1M CYCLES+168 HOURS DATA RETENTION**

CY14B101Q2A (7C1431B5A)	4032722	611055561	CML-RA	168	39	0	
CY14E101PA (7C1431E3A)	4032722	611056066	CML-RA	168	41	0	

**STRESS: DATA RETENTION (150C)**

CY14B101Q2A (7C1431B5A)	4032722	611055561	CML-RA	500	80	0	
CY14B101Q2A (7C1431B5A)	4032722	611055561	CML-RA	1000	80	0	

**STRESS: ESD-HUMAN BODY CIRCUIT PER JEDEC EIA/JESD22-A114-B, 2,200V**

CY14B101Q2A (7C1431B5A)	4032722	611055561	CML-RA	COMP	8	0	
CY14E101Q2A (7C1431E5A)	4032722	611055560	CML-RA	COMP	8	0	
CY14E101J2 (7C1431ECA)	4032722	611056167	CML-RA	COMP	8	0	
CY14E101PA (7C1431E3A)	4032722	611056066	M-PHIL	COMP	8	0	
CY14B101PA (7C1431B3A)	4032722	611056060	M-PHIL	COMP	8	0	
CY14E101Q1A (7C1431E9A)	4032722	611055556	CML-RA	COMP	8	0	
CY14E101PA (7C1431E9A)	4034960	611109616	M-PHIL	COMP	8	0	



## Reliability Test Data

QTP #: 102204

Device	Fab Lot #	Assy Lot #	Assy Loc	Duration	Samp	Rej	Failure Mechanism
<b>STRESS: ESD-CHARGE DEVICE MODEL, 500V</b>							
CY14B101Q2A (7C1431B5A)	4032722	611055561	CML-RA	COMP	9	0	
CY14E101PA (7C1431E3A)	4032722	611056066	M-PHIL	COMP	9	0	
CY14B101PA (7C1431B3A)	4032722	611056060	M-PHIL	COMP	9	0	
CY14E101Q1A (7C1431E9A)	4032722	611055556	CML-RA	COMP	9	0	
<b>STRESS: ESD-MACHINE MODEL, 200V</b>							
CY14E101Q2A (7C1431E5A)	4032722	611055560	CML-RA	COMP	5	0	
CY14E101PA (7C1431E9A)	4034960	611109616	M-PHIL	COMP	5	0	
CY14E101J2 (7C1431E3A)	4034960	611109614	M-PHIL	COMP	5	0	
<b>STRESS: PRESSURE COOKER TEST, 121C, 100%RH, 15 Psig, PRE COND 192 HR 30C/60%RH, MSL3</b>							
CY14B101Q2A (7C1431B5A)	4032722	611055561	CML-RA	168	80	0	
CY14B101Q2A (7C1431B5A)	4032722	611055561	CML-RA	288	80	0	
<b>STRESS: TEMPERATURE CYCLE COND. C, -65C TO 150C, PRE COND 192 HRS 30C/60%RH, MSL3</b>							
CY14B101Q2A (7C1431B5A)	4032722	611055561	CML-RA	500	80	0	
CY14B101Q2A (7C1431B5A)	4032722	611055561	CML-RA	1000	80	0	
<b>STRESS: STATIC LATCH-UP TESTING, 125C, ±140mA</b>							
CY14B101Q2A (7C1431B5A)	4032722	611055561	CML-RA	COMP	6	0	
CY14B101Q1A (7C1431B9A)	4032722	611057658	M-PHIL	COMP	6	0	
CY14E101PA (7C1431E3A)	4032722	611056066	M-PHIL	COMP	6	0	
CY14B101PA (7C1431B3A)	4032722	611056060	M-PHIL	COMP	6	0	
CY14E101Q1A (7C1431E9A)	4032722	611055556	CML-RA	COMP	6	0	
CY14E101PA (7C1431E9A)	4034960	611109616	M-PHIL	COMP	6	0	
CY14B101PA (7C1431B3A)	4034960	611109618	M-PHIL	COMP	6	0	
<b>STRESS: ACOUSTIC-MSL3</b>							
CY14B101Q2A (7C1431B5A)	4032722	611055561	CML-RA	COMP	15	0	
<b>STRESS: SER – ALPHA PARTICLE, 3-TEPM, 3-VOLTAGE, @ 85C, Vcc Nom</b>							
CY14E101Q2A (7C14104B)	4034960	611109692	M-PHIL	COMP	3	0	



## Reliability Test Data

QTP #: 122802

Device	Fab Lot #	Assy Lot #	Assy Loc	Duration	Samp	Rej	Failure Mechanism
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**STRESS: HIGH TEMP DYNAMIC OPERATING LIFE-EARLY FAILURE RATE, 125C, 5.5V, Vcc Max**

CY14ME064Q2A (7C1436B5A)	4228534	611230237	CML-RA	96	1201	0	
CY14ME064Q2A (7C1436B5A)	4229040	611230238	CML-RA	96	1939	0	

**STRESS: HIGH TEMP DYNAMIC OPERATING LIFE-EARLY FAILURE RATE, 125C, 3.3V, Vcc Max**

CY14MB064Q2A (7C1436B5A)	4229040	611230171	CML-RA	96	697	0	
CY14MB064Q2A (7C1436B5A)	4228534	611230172	CML-RA	96	686	0	

**STRESS: HIGH TEMP DYNAMIC OPERATING LIFE-LATENT FAILURE RATE, 125C, 5.5V, Vcc Max**

CY14ME064Q2A (7C1436B5A)	4228534	611230237	CML-RA	168	108	0	
CY14ME064Q2A (7C1436B5A)	4229040	611230238	CML-RA	168	108	0	

**STRESS: HIGH TEMP DYNAMIC OPERATING LIFE-LATENT FAILURE RATE, 125C, 3.3V, Vcc Max**

CY14MB064Q2A (7C1436B5A)	4229040	611230171	CML-RA	168	88	0	
CY14MB064Q2A (7C1436B5A)	4228534	611230172	CML-RA	168	88	0	

**STRESS: Pre-/ Post HIGH TEMP DYNAMIC OPERATING LIFE-LATENT FAILURE RATE CHAR**

CY14ME064Q2A (7C1436B5A)	4228534	611230237	CML-RA	COMP	10	0	
CY14ME064Q2A (7C1436B5A)	4229040	611230238	CML-RA	COMP	10	0	
CY14MB064Q2A (7C1436B5A)	4229040	611230171	CML-RA	COMP	10	0	
CY14MB064Q2A (7C1436B5A)	4228534	611230172	CML-RA	COMP	10	0	

**STRESS: ESD-HUMAN BODY CIRCUIT PER JEDEC EIA/JESD22-A114-B, 2,200V**

CY14MB064Q2A (7C1436B5A)	4228534	611229009	CML-RA	COMP	8	0	
CY14MB064Q2A (7C1436B5A)	4228534	611229013	CML-RA	COMP	8	0	
CY14MB064Q2A (7C1436B5A)	4228534	611229012	CML-RA	COMP	8	0	

**STRESS: ESD-CHARGE DEVICE MODEL, 500V**

CY14MB064Q2A (7C1436B5A)	4228534	611229009	CML-RA	COMP	9	0	
CY14MB064Q2A (7C1436B5A)	4228534	611229013	CML-RA	COMP	9	0	
CY14MB064Q2A (7C1436B5A)	4228534	611229012	CML-RA	COMP	9	0	

**STRESS: ESD-MACHINE MODEL, 200V**

CY14MB064Q2A (7C1436B5A)	4228534	611229009	CML-RA	COMP	5	0	
CY14MB064Q2A (7C1436B5A)	4228534	611229013	CML-RA	COMP	5	0	



## Reliability Test Data

QTP #: 122802

Device	Fab Lot #	Assy Lot #	Assy Loc	Duration	Samp	Rej	Failure Mechanism
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**STRESS: STATIC LATCH-UP TESTING, 85C/125C, ±140mA**

CY14MB064Q2A (7C1436B5A)	4228534	611229011	CML-RA	COMP	6	0	
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CY14MB064Q2A (7C1436B5A)	4228534	611229012	CML-RA	COMP	6	0	
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**STRESS: ACOUSTIC-MSL3**

CY14MB064Q2A (7C1436B5A)	4228534	611229009	CML-RA	COMP	15	0	
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**STRESS: PRESSURE COOKER TEST, 121C, 100%RH, 15 Psig, PRE COND 192 HR 30C/60%RH, MSL3**

CY14MB064Q2A (7C1436B5A)	4228534	611229009	CML-RA	168	76	0	
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**STRESS: TEMPERATURE CYCLE COND. C, -65C TO 150C, PRE COND 192 HRS 30C/60%RH, MSL3**

CY14MB064Q2A (7C1436B5A)	4228534	611229009	CML-RA	500	77	0	
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## Reliability Test Data

QTP #: 113005

Device	Fab Lot #	Assy Lot #	Assy Loc	Duration	Samp	Rej	Failure Mechanism
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**STRESS: HIGH TEMP DYNAMIC OPERATING LIFE-EARLY FAILURE RATE, 125C, 5.5V, Vcc Max**

CY14ME064Q2B (7C1446E5A)	4231244	611236507	CML-RA	96	3330	0	
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**STRESS: HIGH TEMP DYNAMIC OPERATING LIFE-EARLY FAILURE RATE, 125C, 3.3V, Vcc Max**

CY14MB064Q2B (7C1446B5A)	4231244	611236508	CML-RA	96	594	0	
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CY14MB064Q2B (7C1446B5A)	4231244	611236522	CML-RA	96	693	0	
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**STRESS: HIGH TEMP DYNAMIC OPERATING LIFE-LATENT FAILURE RATE, 125C, 5.5V, Vcc Max**

CY14ME064Q2B (7C1446E5A)	4231244	611236507	CML-RA	168	108	0	
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CY14ME064Q2B (7C1446E5A)	4231244	611236507	CML-RA	500	108	0	
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CY14ME064Q2B (7C1446E5A)	4231244	611236507	CML-RA	1000	108	0	
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**STRESS: HIGH TEMP DYNAMIC OPERATING LIFE-LATENT FAILURE RATE, 125C, 3.3V, Vcc Max**

CY14MB064Q2B (7C1446B5A)	4231244	611236508	CML-RA	168	88	0	
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**STRESS: Pre-/ Post HIGH TEMP DYNAMIC OPERATING LIFE-LATENT FAILURE RATE CHAR**

CY14ME064Q2B (7C1446E5A)	4231244	611236507	CML-RA	168	16	0	
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CY14MB064Q2B (7C1446B5A)	4231244	611236508	CML-RA	168	16	0	
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**STRESS: ESD-HUMAN BODY CIRCUIT PER JEDEC EIA/JESD22-A114-B, 2,200V**

CY14ME064Q1B (7C1446E9A)	4231244	611236512	CML-RA	COMP	8	0	
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CY14ME064Q2B (7C1446E5A)	4231244	611236507	CML-RA	COMP	8	0	
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CY14ME064J2A (7C14EC46A)	4231244	611236510	CML-RA	COMP	8	0	
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**STRESS: ESD-CHARGE DEVICE MODEL, 500V**

CY14ME064Q1B (7C1446E9A)	4231244	611236512	CML-RA	COMP	9	0	
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**STRESS: ESD-MACHINE MODEL, 200V**

CY14ME064Q1B (7C1446E9A)	4231244	611236512	CML-RA	COMP	5	0	
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CY14ME064Q2B (7C1446E5A)	4231244	611236507	CML-RA	COMP	5	0	
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CY14ME064J2A (7C14EC46A)	4231244	611236510	CML-RA	COMP	5	0	
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**STRESS: STATIC LATCH-UP TESTING, 85C, ±140mA**

CY14ME064Q1B (7C1446E9A)	4231244	611236512	CML-RA	COMP	6	0	
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CY14MB064Q1B (7C1446B9A)	4231244	611236511	CML-RA	COMP	6	0	
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**STRESS: DYNAMIC LATCH-UP TESTING, 125C (3V part – 5.5V, 5V Part – 8V)**

CY14ME064Q1B (7C1446E9A)	4231244	611236512	CML-RA	COMP	1	0	
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CY14MB064Q1B (7C1446B9A)	4231244	611236511	CML-RA	COMP	1	0	
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Document Number: 001-85611

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**	3863005	NSR	Initial spec release
*A	5106807	ILZ	No Change. Sunset Review
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